

Title (en)

RESIN MOLDED ARTICLE MANUFACTURING DEVICE, AND MANUFACTURING DEVICE CONTROL METHOD

Title (de)

VORRICHTUNG ZUR HERSTELLUNG EINES HARZFORMTEILS UND VERFAHREN ZUR STEUERUNG EINER HERSTELLUNGSVORRICHTUNG

Title (fr)

DISPOSITIF DE FABRICATION D'ARTICLE MOULÉ EN RÉSINE, ET PROCÉDÉ DE COMMANDE DE DISPOSITIF DE FABRICATION

Publication

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Application

**EP 20788375 A 20200408**

Priority

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Abstract (en)

An object of the present disclosure is to provide a manufacturing apparatus for manufacturing a resin molded article and a control method for controlling the manufacturing apparatus, capable of stably manufacturing a resin molded article of good quality even with a short injection molding time. A manufacturing apparatus 100 for manufacturing a resin molded article 1 includes: an injection molding part 10 configured to inject resin into an injection mold 12 and injection-mold the resin molded article 1; a control unit 13 configured to control the injection by the injection molding part 10; a calculation unit 14 configured to calculate a pressure reduction curve for reducing a pressure generated by the injection; and an input unit 15 via which a user inputs a condition of the pressure reduction curve, in which the control unit 13 is configured to control the injection based on the pressure reduction curve.

IPC 8 full level

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